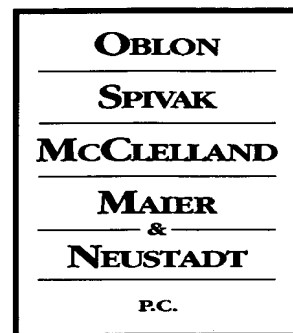




Docket No.: 240111US0

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313



ATTORNEYS AT LAW

RE: Application Serial No.: 10/619,632

Applicants: Takeshi SANO, et al.

Filing Date: July 16, 2003

For: ELASTIC CONDUCTIVE RESIN, AND
ELECTRONIC DEVICE INCLUDING ELASTIC
CONDUCTIVE BUMPS MADE OF THE ELASTIC
CONDUCTIVE RESIN

Group Art Unit: 2841

Examiner: I. B. Patel

SIR:

Attached hereto for filing are the following papers:

Response to Restriction Requirement

Our check in the amount of \$0.00 is attached covering any required fees. In the event any variance exists between the amount enclosed and the Patent Office charges for filing the above-noted documents, including any fees required under 37 C.F.R. 1.136 for any necessary Extension of Time to make the filing of the attached documents timely, please charge or credit the difference to our Deposit Account No. 15-0030. Further, if these papers are not considered timely filed, then a petition is hereby made under 37 C.F.R. 1.136 for the necessary extension of time. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
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DOCKET NO: 240111US0



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
TAKESHI SANO, ET AL. : EXAMINER: I. B. PATEL
SERIAL NO: 10/619,632 :
FILED: JULY 16, 2003 : GROUP ART UNIT: 2841
FOR: ELASTIC CONDUCTIVE RESIN, :
AND ELECTRONIC DEVICE
INCLUDING ELASTIC CONDUCTIVE
BUMPS MADE OF THE ELASTIC
CONDUCTIVE RESIN

RESPONSE TO RESTRICTION REQUIREMENT

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

In response to the Restriction Requirement mailed July 1, 2005, Applicants elect, with traverse, Group I: Claims 1-4, drawn to an elastic conductive resin composition.

REMARKS

The Examiner is requiring restriction of the above-identified application as follows:

Group I: Claims 1-4, drawn to an elastic conductive resin composition;
Group II: Claims 5-19, and 22-23, drawn to an electronic device; and
Group III: Claims 20 and 21, drawn to a method of forming a bump on an electrode.

Applicants have elected, with traverse, Group I: Claims 1-4, drawn to an elastic conductive resin composition.